



GT75HF120T1NH

IGBT Module

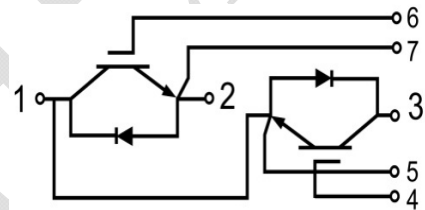
Features:

- Field Stop Trench Gate IGBT
- Short Circuit Rated > 10 μ s
- Low Saturation Voltage
- Low Switching Loss
- 100% RBSOA Tested (2 \times I_c)
- Low Stray Inductance
- Lead Free, Compliant with RoHS Requirement



Applications:

- Industrial Inverters
- Induction Heating



IGBT, Inverter

Maximum Rated Values of IGBT (T_C=25°C unless otherwise specified)

V _{CEs}	Collector-Emitter Blocking Voltage		1200	V
V _{GES}	Gate-Emitter Voltage		±20	V
I _c	Continuous Collector Current	T _C = 100°C	75	A
		T _C = 25°C	140	A
I _{CM}	Repetitive Peak Collector Current	T _J = 175°C	150	A
t _{sc}	Short Circuit Withstand Time		>10	μs
P _D	Maximum Power Dissipation per IGBT	T _C = 25°C T _{Jmax} = 175°C	520	W



Electrical Characteristics of IGBT ($T_C=25^\circ\text{C}$ unless otherwise specified)

Static Characteristics

Symbol	Description	Conditions	Min	Typ	Max	Unit
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C = 1\text{mA}, V_{CE} = V_{GE}$	5.0	5.7	6.8	V
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C = 75\text{A}, V_{GE} = 15\text{V}$	$T_J = 25^\circ\text{C}$	1.85	2.05	V
			$T_J = 125^\circ\text{C}$	2.15		V
I_{CES}	Collector-Emitter Leakage Current	$V_{GE} = 0\text{V}, V_{CE} = V_{CES}, T_J = 25^\circ\text{C}$			1	mA
I_{GES}	Gate-Emitter Leakage Current	$V_{GE} = \pm 20\text{V}, V_{CE} = 0\text{V}, T_J = 25^\circ\text{C}$			200	nA
C_{ies}	Input Capacitance	$V_{CE} = 25\text{V}, V_{GE} = 0\text{V}, f = 1\text{MHz}$		6.40		nF
C_{oes}	Output Capacitance			0.44		nF
C_{res}	Reverse Transfer Capacitance			0.06		nF

Switching Characteristics

$t_{d(on)}$	Turn-on Delay Time	$V_{CC} = 600\text{V}, I_C = 75\text{A}, R_{Gon} = 10\Omega, V_{GE} = \pm 15\text{V},$ Inductive Load	$T_J = 25^\circ\text{C}$	308		ns
			$T_J = 125^\circ\text{C}$	275		
t_r	Rise Time	$V_{CC} = 600\text{V}, I_C = 75\text{A}, R_{Gon} = 10\Omega, V_{GE} = \pm 15\text{V},$ Inductive Load	$T_J = 25^\circ\text{C}$	80		ns
			$T_J = 125^\circ\text{C}$	76		
$t_{d(off)}$	Turn-off Delay Time	$V_{CC} = 600\text{V}, I_C = 75\text{A}, R_{Goff} = 10\Omega, V_{GE} = \pm 15\text{V},$ Inductive Load	$T_J = 25^\circ\text{C}$	208		ns
			$T_J = 125^\circ\text{C}$	204		
t_f	Fall Time	$V_{CC} = 600\text{V}, I_C = 75\text{A}, R_{Goff} = 10\Omega, V_{GE} = \pm 15\text{V},$ Inductive Load	$T_J = 25^\circ\text{C}$	210		ns
			$T_J = 125^\circ\text{C}$	335		
E_{on}	Turn-on Switching Loss	$V_{CC} = 600\text{V}, I_C = 75\text{A}, R_{Gon} = 10\Omega, V_{GE} = \pm 15\text{V},$ $di/dt = 840\text{A}/\mu\text{s} (T_J = 125^\circ\text{C}),$ Inductive Load	$T_J = 25^\circ\text{C}$	4.85		mJ
			$T_J = 125^\circ\text{C}$	5.95		
E_{off}	Turn-off Switching Loss	$V_{CC} = 600\text{V}, I_C = 75\text{A}, R_{Goff} = 10\Omega, V_{GE} = \pm 15\text{V},$ $du/dt = 5275\text{V}/\mu\text{s} (T_J = 125^\circ\text{C}),$ Inductive Load	$T_J = 25^\circ\text{C}$	3.67		mJ
			$T_J = 125^\circ\text{C}$	5.67		
Q_g	Total Gate Charge	$V_{GE} = +15\text{V} \dots -15\text{V}$	$T_J = 25^\circ\text{C}$	330		nC
$R_{g \text{ internal}}$	Internal Gate Resistance		$T_J = 25^\circ\text{C}$	10		Ω
RBSOA	Reverse Bias Safe Operation Area	$I_C = 150\text{A}, V_{CC} = 1050\text{V}, V_p = 1200\text{V},$ $R_{Goff} = 10\Omega, V_{GE} = +15\text{V to } 0\text{V}, T_J = 150^\circ\text{C}$	Trapezoid			
SCSOA	SCSOA	$V_{CC} = 600\text{V}, V_{GE} = 15\text{V},$ $T_J = 125^\circ\text{C}$	10			μs
$R_{\theta JC}$	IGBT Thermal Resistance: Junction-To-Case				0.289	$^\circ\text{C}/\text{W}$



Diode, Inverter

Maximum Rated Values of Diode ($T_C=25^\circ\text{C}$ unless otherwise specified)

V_{RRM}	Repetitive Peak Reverse Voltage	1200	V
I_F	Diode Continuous Forward Current	75	A
I_{FM}	Diode Maximum Forward Current	150	A

Electrical Characteristics of Diode ($T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Description	Conditions	Min	Typ	Max	Unit
V_{FM}	Forward Voltage	$I_F = 75\text{A}$	$T_J=25^\circ\text{C}$	2.50		V
			$T_J=125^\circ\text{C}$	2.50		
t_{rr}	Reverse Recovery Time	$I_F=75\text{A},$ $-di_F/dt = 1040\text{A}/\mu\text{s}(T_J=125^\circ\text{C}),$ $V_{rr} = 600\text{V},$ $V_{GE} = -15\text{V}$	$T_J=25^\circ\text{C}$	178		ns
			$T_J=125^\circ\text{C}$	324		
I_{rr}	Peak Reverse Recovery Current	$I_F=75\text{A},$ $-di_F/dt = 1040\text{A}/\mu\text{s}(T_J=125^\circ\text{C}),$ $V_{rr} = 600\text{V},$ $V_{GE} = -15\text{V}$	$T_J=25^\circ\text{C}$	44.0		A
			$T_J=125^\circ\text{C}$	53.1		
Q_{rr}	Reverse Recovery Charge	$I_F=75\text{A},$ $-di_F/dt = 1040\text{A}/\mu\text{s}(T_J=125^\circ\text{C}),$ $V_{rr} = 600\text{V},$ $V_{GE} = -15\text{V}$	$T_J=25^\circ\text{C}$	3.80		μC
			$T_J=125^\circ\text{C}$	7.80		
E_{rec}	Reverse Recovery Energy	$I_F=75\text{A},$ $-di_F/dt = 1040\text{A}/\mu\text{s}(T_J=125^\circ\text{C}),$ $V_{rr} = 600\text{V},$ $V_{GE} = -15\text{V}$	$T_J=25^\circ\text{C}$	1.18		mJ
			$T_J=125^\circ\text{C}$	2.75		
$R_{\theta JC}$	Diode Thermal Resistance: Junction-To-Case				0.428	$^\circ\text{C}/\text{W}$



Module

Symbol	Description	Min.	Typ.	Max.	Units
V _{iso}	Isolation Voltage (All Terminals Shorted)	f =50Hz, 1minute	2500		V
T _J	Maximum Junction Temperature			175	°C
T _{JOP}	Maximum Operating Junction Temperature Range	-40		+150	°C
T _{stg}	Storage Temperature	-40		+125	°C
CTI	Comparative Tracking Index	200			
R _{θCS}	Case-to-Sink Thermally (Conductive Grease Applied)			0.07	°C/W
T	Power Terminals Screw:M5	3.0		5.0	N·m
T	Mounting Screw:M6	4.0		6.0	N·m
G	Weight		150		g

Ordering Information Table

Device code	G	T	75	HF	120	T1N	H
	①	②	③	④	⑤	⑥	⑦

- ① - IGBT Module
- ② - Trench , Low Switching Losses IGBT
- ③ - Rated Current (75=75A)
- ④ - Circuit Configuration (Half Bridge)
- ⑤ - Rated Voltage (120=1200V)
- ⑥ - Package Type
- ⑦ - Test Level (Pass the Important Reliability Test-Industrial Grade)

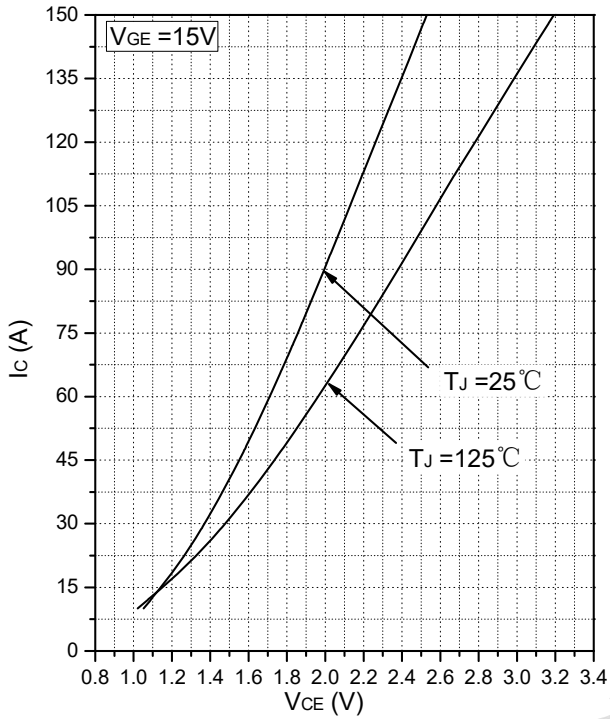


Fig.1 Typical Saturation Voltage Characteristics

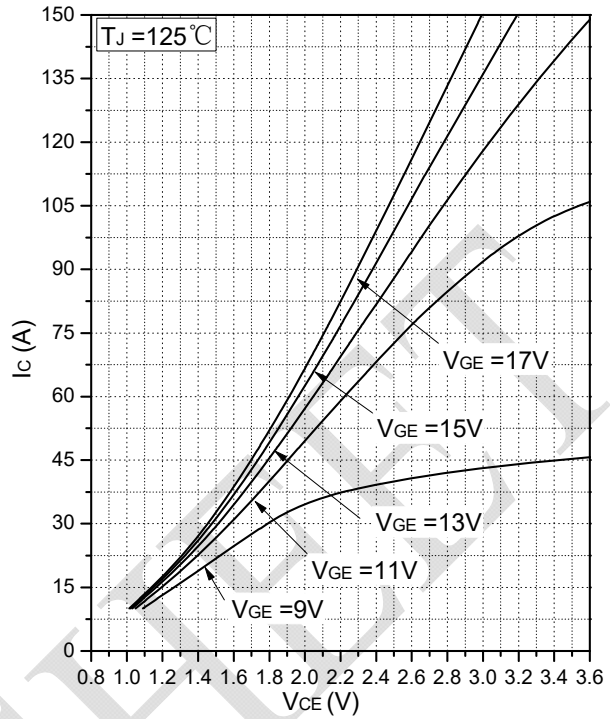


Fig.2 Typical Output Characteristics

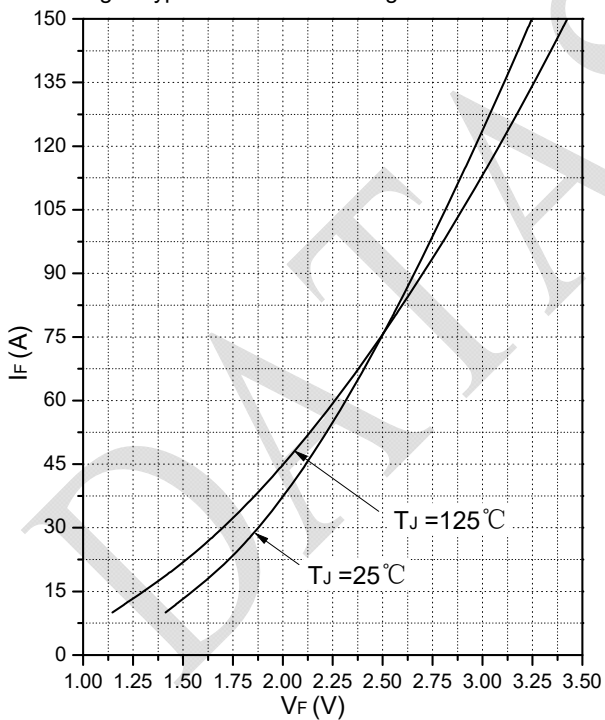


Fig.3 Forward Characteristics of Diode

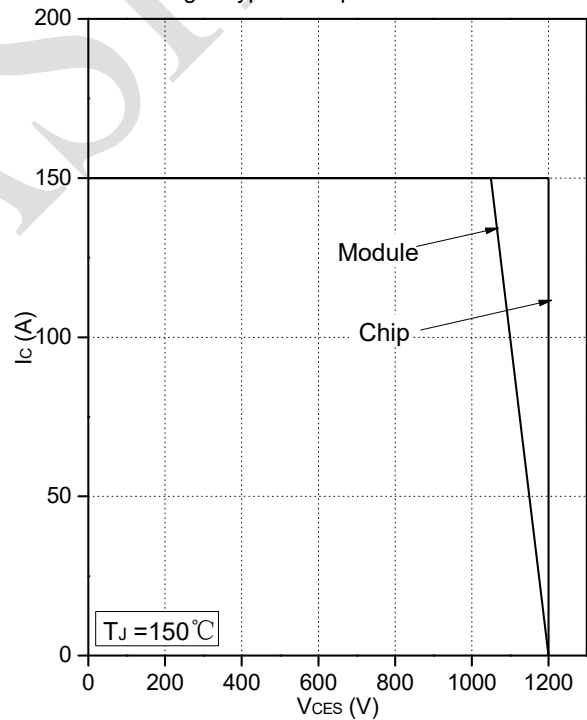


Fig.4 Reverse Bias Safe Operation Area (RBSOA)

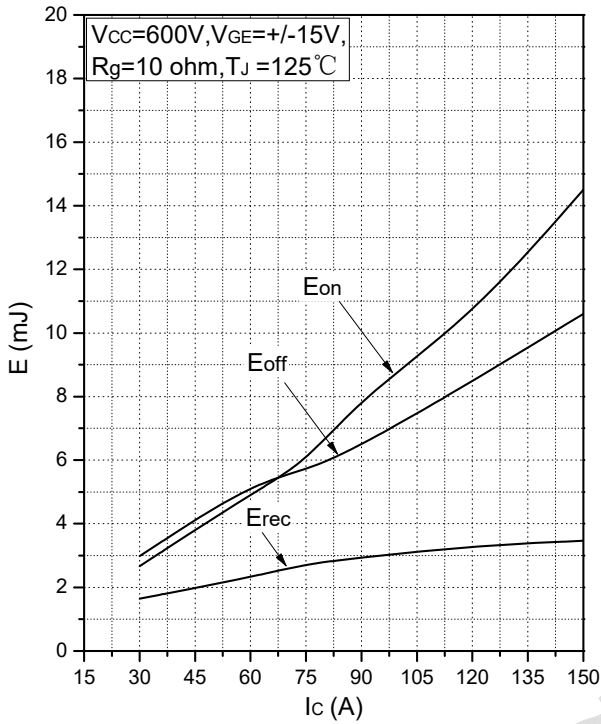


Fig.5 Typical Switching Loss vs. Collector Current

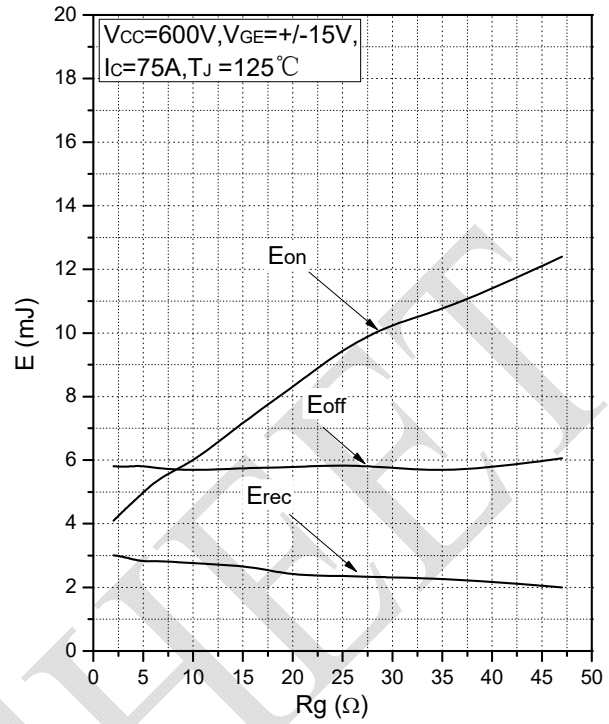


Fig.6 Typical Switching Loss vs. Gate Resistance

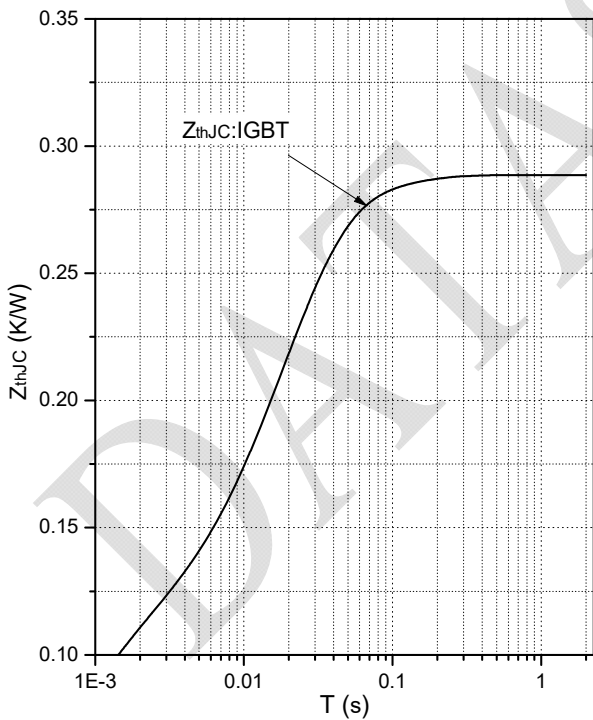


Fig.7 Transient Thermal Impedance (IGBT)

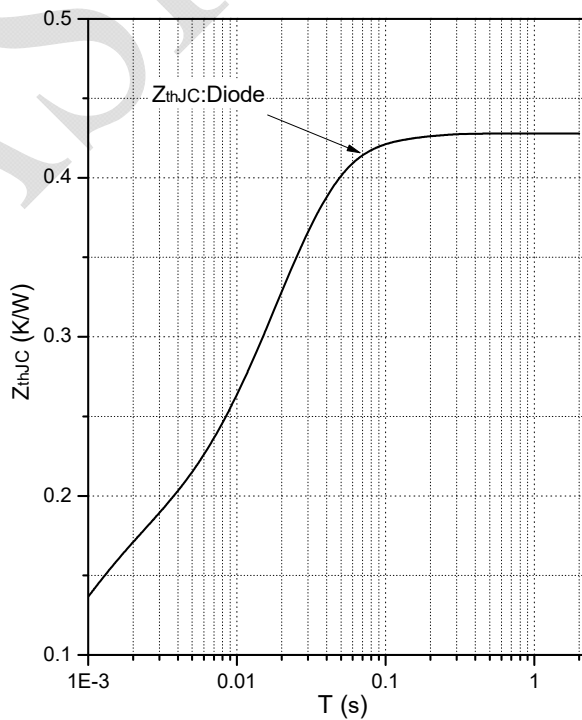


Fig.8 Transient Thermal Impedance (Diode)

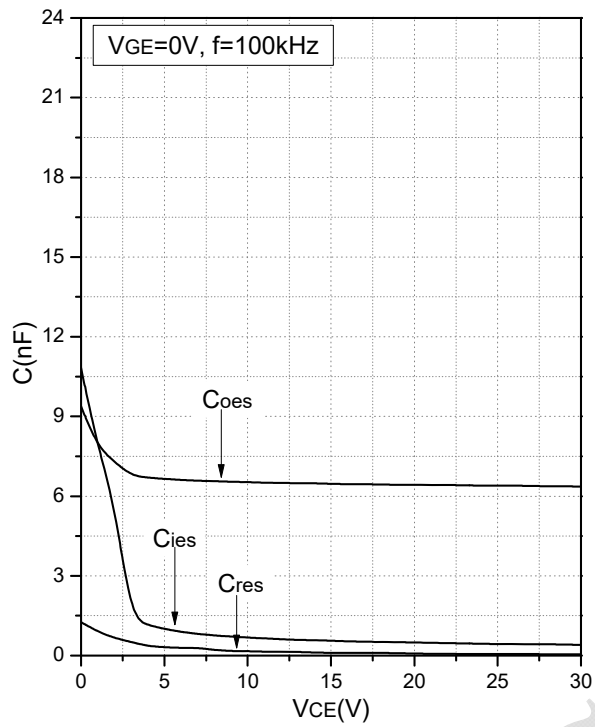
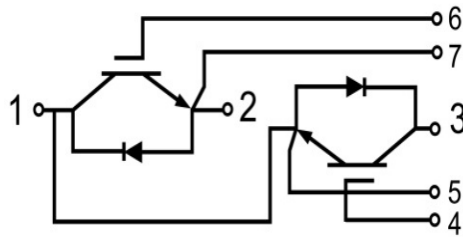


Fig.9 Capacitance Characteristics

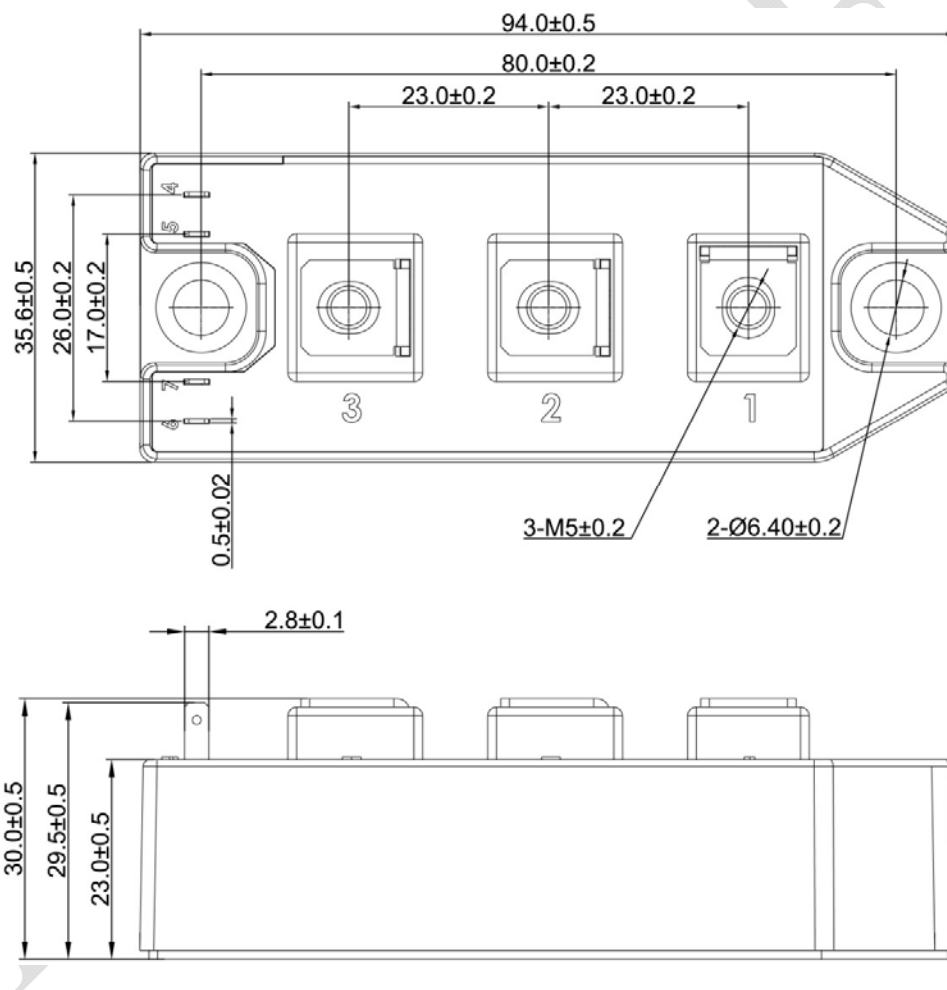
DATA SHEET



Internal Circuit



Package Outline (Unit: mm):





Date	Revision	Notes
03/06/2021	01	Initial Release
08/01/2023	02	Add Graph of Capacitance Characteristics

Announcements

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The released datasheet would be issued with “REV.” + “alphabet characters”.